



Product/Process Change Notice - PCN 22_0053 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: LTM4631 Notification of qualification for additional mold compound and additional assembly location ASE Korea.

Publication Date: 15-Mar-2022

Effectivity Date: 17-Jun-2022 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release: LTM4631 Notification of qualification for additional mold compound and additional assembly location ASE Korea.

Description Of Change:

- A new mold compound has been qualified in LTM4631 which is the next generation mold compound going forward. The new mold compound uses fine filler and facilitates the filling of tighter spaces.
- ADI is adding ASE Korea as an alternate assembly facility for LTM4631.

Reason For Change:

- Higher density component assembly in a uModule substrate requires mold filling in tighter spaces between and underneath components. The new mold compound facilitates this task which also improves assembly yield.
- To qualify ASE Korea as an alternate assembly site to ensure the continuous availability of a reliable source of product supply.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change is transparent in customer applications since there is no change in the form, fit, function, quality, or reliability of the products. The product datasheet is unchanged.

Product Identification *(this section will describe how to identify the changed material)*

Production shipment of the product incorporating the new material will begin no sooner than the effective date and will be identified by datecode.

Summary of Supporting Information:

The qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_22_0053_Rev_-_LTM4631 G311E PCN Rel Data.pdf

Attachment 2: Type: Qualification Results Summary

ADI_PCN_22_0053_Rev_-_LTM4631 BGA ASE Transfer PCN Rel Data.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (5)**

LTM4631 / LTM4631EV#PBF

LTM4631 / LTM4631EY#PBF

LTM4631 / LTM4631IV#PBF

LTM4631 / LTM4631IY

LTM4631 / LTM4631IY#PBF

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	15-Mar-2022	17-Jun-2022	Initial Release: LTM4631 Notification of qualification for additional mold compound and additional assembly location ASE Korea.

Analog Devices, Inc.

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